



DFLU1400

1.0A SURFACE MOUNT SUPER-FAST RECTIFIER PowerDf®123

Features

- Glass Passivated Die Construction
- Super-Fast Recovery Time for High Efficiency
- Low Forward-Voltage Drop and High Current Capability
- Patented Interlocking Clip Design for High Surge Capacity, US Patent #7,095,113
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: PowerDI[®]123
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 63
- Weight: 0.011 grams (Approximate)



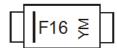
Ordering Information (Note 4)

Device	Packaging	Shipping	
DFLU1400-7	PowerDI®123	3,000/Tape & Reel	

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



F16 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018
Code	S	T	U	V	W	Χ	Υ	Z	Α	В	С	D	Е	F
Мо	nth	Jan	Feb	Mar	Apr	May	/ Ju	n J	ul	Aug	Sep	Oct	Nov	Dec
Co	de	1	2	3	4	5	6		7	8	9	0	N	D

PowerDI is a registered trademark of Diodes Incorporated



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 9)	V _{RRM} V _{RWM} V _R	400	V
RMS Reverse Voltage	V _{R(RMS)}	280	V
Average Rectified Output Current	Io	1.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	30	A

Thermal Characteristics

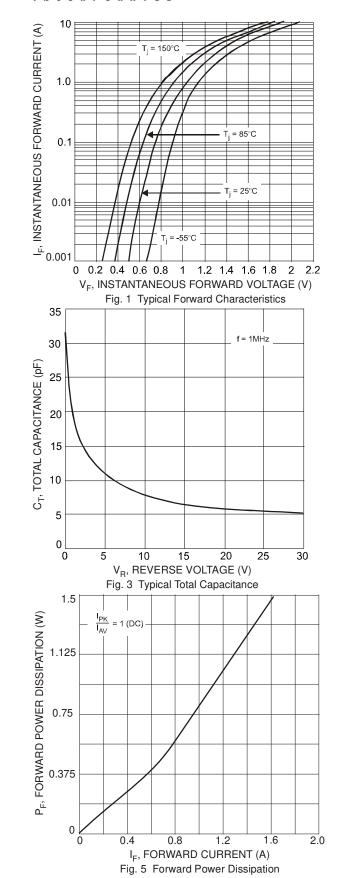
Characteristic		Symbol	Тур	Max	Unit
Power Dissipation (Note 5)	$pT_{A} = +25^{\circ}C$	P_{D}	_	1.0	W
Thermal Resistance Junction to Ambient (Note 5) @	$DT_A = +25^{\circ}C$	$R_{\Theta JA}$	117	_	°C/W
Thermal Resistance Junction to Soldering Point (Note 7)	Rejs	_	6	°C/W	
Operating and Storage Temperature Range	T _{j,} T _{STG}	-65 to	+150	°C	

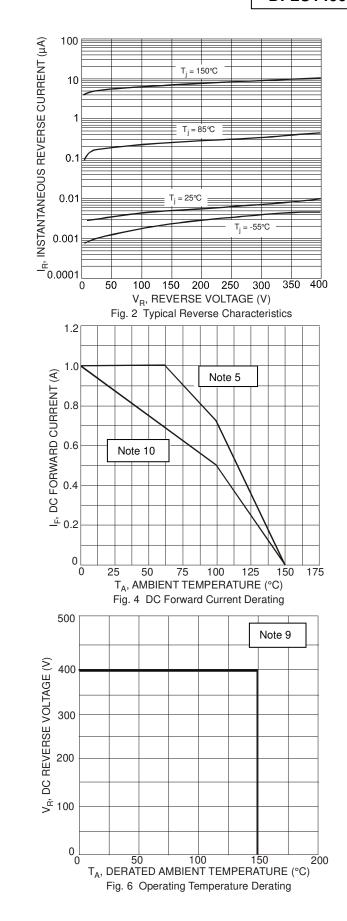
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Minimum Reverse Breakdown Voltage	@I _R =5μA	$V_{(BR)R}$	400	V
Maximum Forward Voltage Drop	$@I_F = 1.0A$	V_{FM}	1.25	V
Peak Reverse Current	$@T_A = +25^{\circ}C$	I	5.0	μA
at Rated DC Blocking Voltage (Note 9)	$@T_A = +100^{\circ}C$	IRM	200	μΑ
Maximum Reverse Recovery Time (Note 8)		t _{rr}	25	ns
Typical Total Capacitance (f = 1MHz, V _R = 4VDC)		C_{T}	14	pF

- Notes: 5. Device mounted on 1" x 1", Polymide PCB; 2 oz. Cu pad layout as shown on Diodes Inc. suggested pad layout document AP02001.pdf.
 - 6. RoHS revision 13.2.2003. Glass and high temperature solder exemptions applied; see EU Directive Annex Notes 5 and 7.
 - 7. Theoretical R_{6JS} calculated from the top center of the die straight down to the PCB cathode tab solder junction.
 - 8. Measured with I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A.
 - 9. Short duration pulse test used to minimize self-heating effect.
 - 10. Device mounted on FR-4 PCB, 2oz. Cu pad layout as shown on Diodes Inc. suggested pad layout document AP02001.pdf.



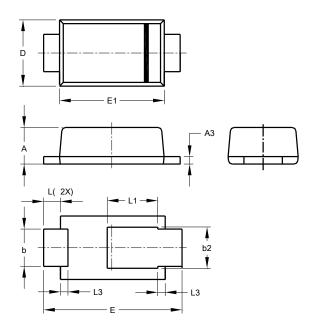






Package Outline Dimensions

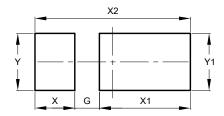
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



POWERDI®123						
Dim	Min	Max	Тур			
Α	0.93	1.00	0.98			
A3	0.15	0.25	0.20			
b	0.85	1.25	1.00			
b2	1.025	1.125	1.10			
D	1.63	1.93	1.78			
E	3.50	3.90	3.70			
E1	2.60	3.00	2.80			
L	0.40	0.50	0.45			
L1	1.25	1.40	1.35			
L3	0.125	0.275	0.20			
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
G	0.65		
Х	1.05		
X1	2.40		
X2	4.10		
Y	1.50		
Y1	1.50		



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